

/ Revised record

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
A	2019-2-15	所有	首次制定	蓝月葵	梁晓峰
B	2021-1-27	4/7	更新外形图 e0.5-0.7 改为 0.5-0.8 ,包装资料 5 盒改为 7 盒	黄超	刘晓荣

/ Descriptions

1.2A MBF
1.2A Surface Mount Glass Passivated Bridge Rectifier, MBF thin package。

/ Features

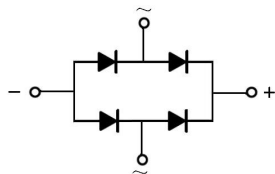
100V~1000V 1.2A

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current: 1.2A, High Surge Current Capability, Designed for Surface Mount Application.Halogen free product.

/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

/ Marking

See Marking Instructions.

Rev.B Jan-2021

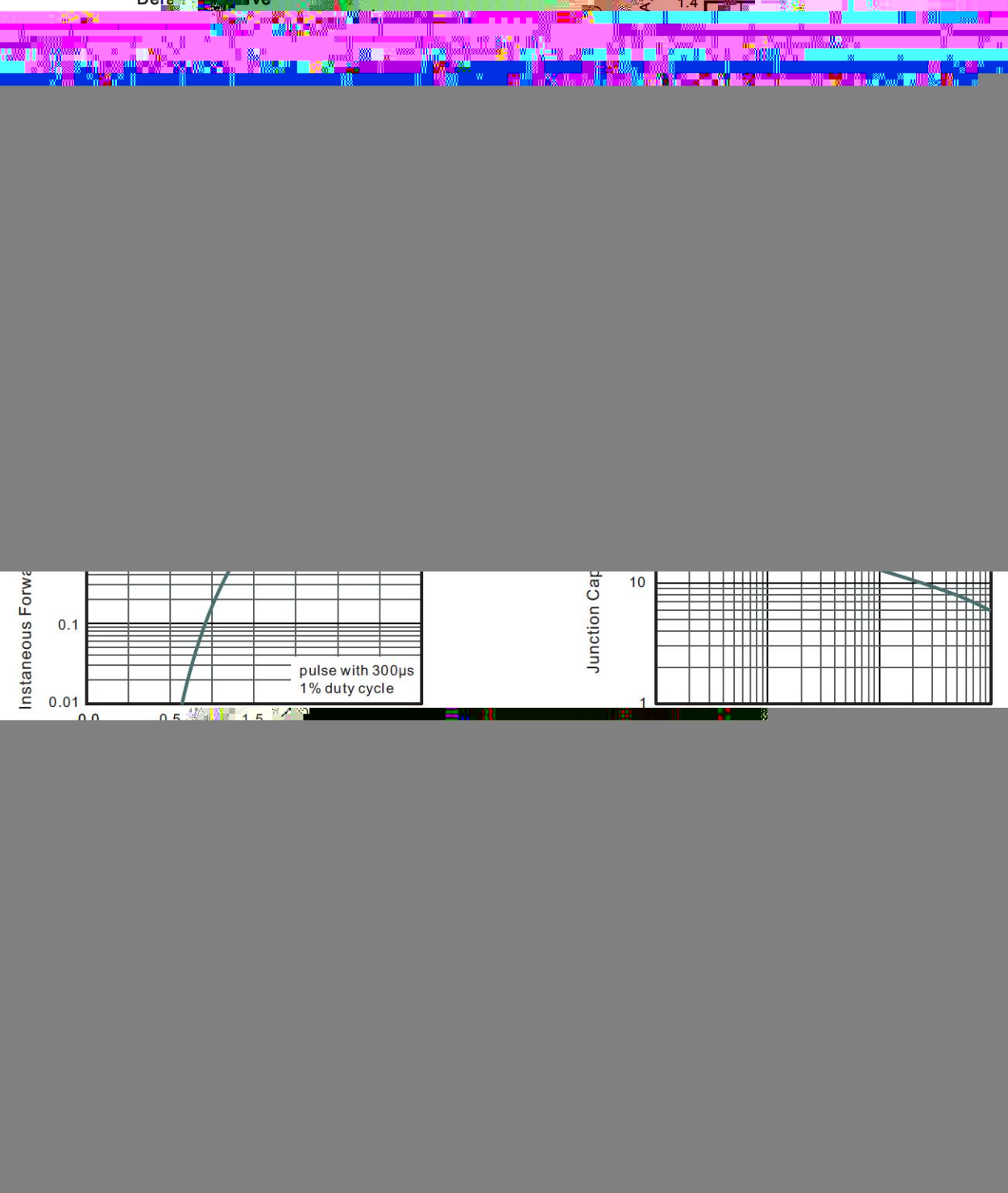


<http://www.fsbrec.com>

/ Electrical Characteristic Curve

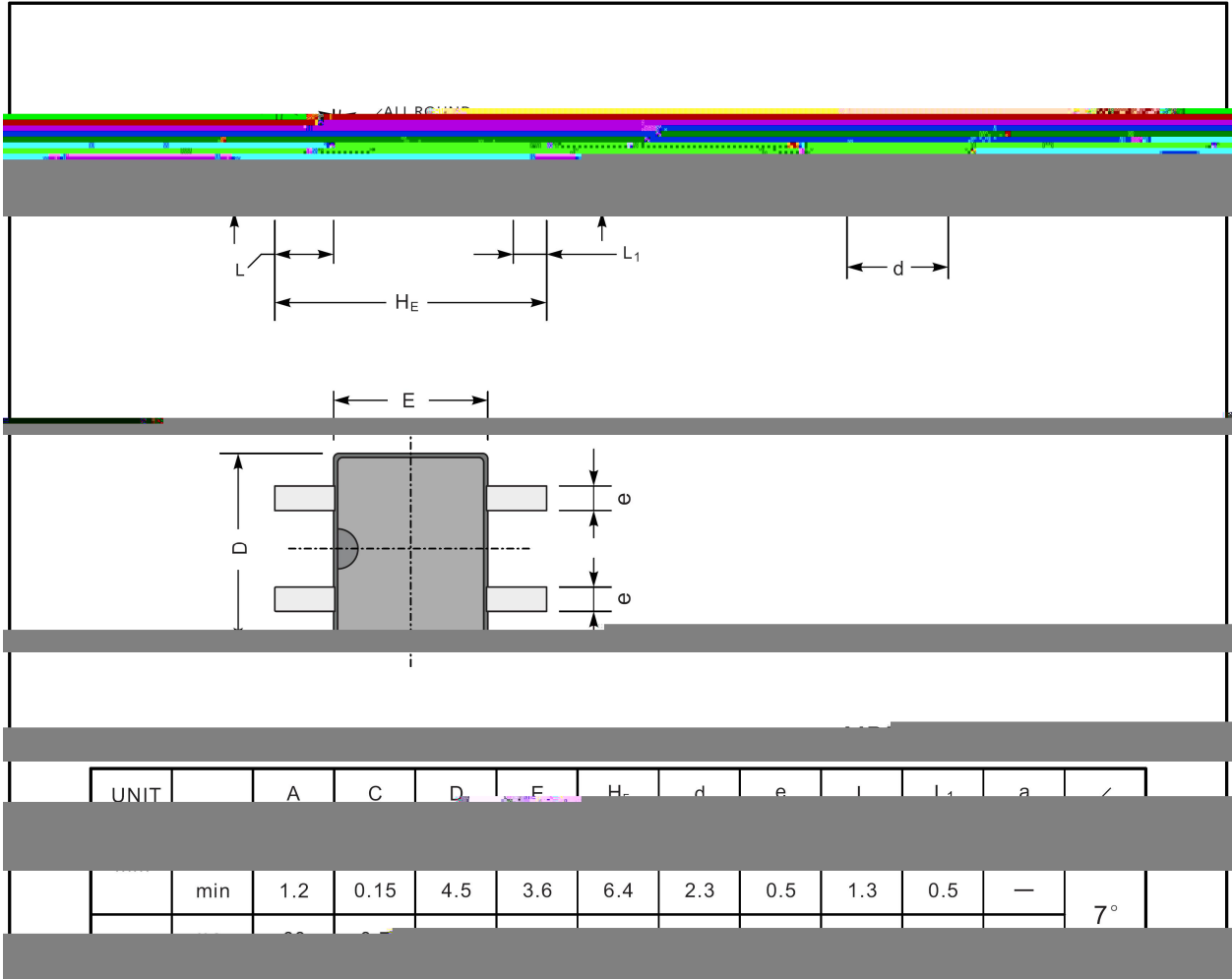
Fig.1 Average Rectified Output Current
Derating Curve

Fig.2 Typical Reverse Characteristics



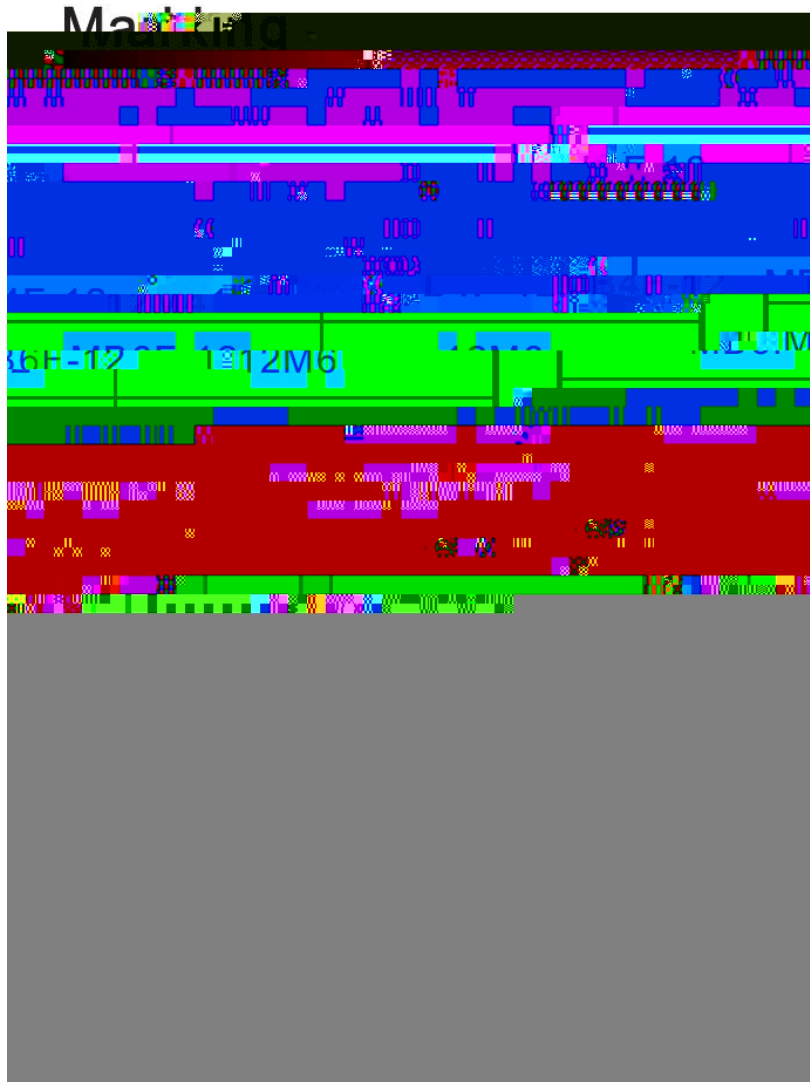
/ Package Dimensions

MBF

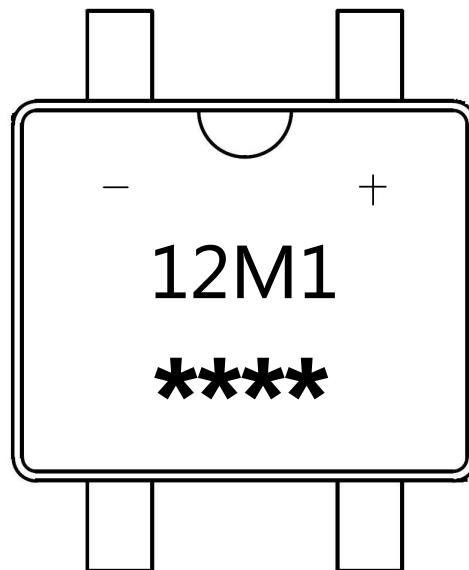




/ Marking Instructions



/ Marking Instructions



12M1

1 *

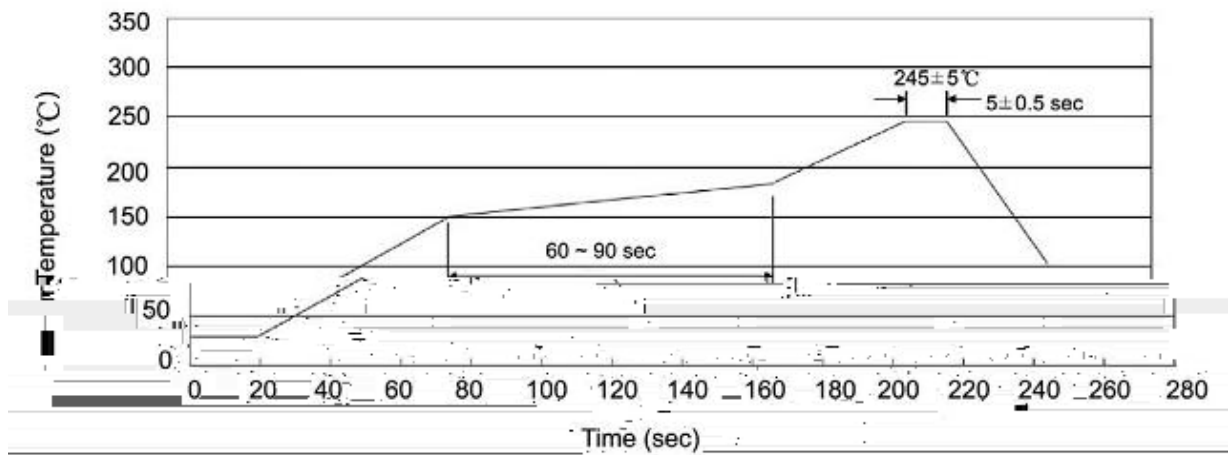
3 *

Note:

12M1 Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C

10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱